

L Number	Hits	Search Text	DB	Time stamp
1	290420	circuit near board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 12:16
2	213975	multilayer or (multi near layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 10:10
3	12670	(circuit near board) near7 (multilayer or (multi near layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 12:49
5	104030	("156").CLAS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 10:11
11	343	((circuit near board) near7 (multilayer or (multi near layer))) and ("156").CLAS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 12:17
20	4	("3573126" "3681171" "3684610" "3960635").PN.	USPAT	2003/10/17 12:13
21	18	4290838.URPN.	USPAT	2003/10/17 12:13
28	9	("3932250" "4875283" "5153050" "5160567" "5256474" "5286330" "6127051" "6174591" "6179947").PN.	USPAT	2003/10/17 12:19
29	0	6537412.URPN.	USPAT	2003/10/17 12:20
32	6	("4180608" "4715116" "4722765" "4781969" "4872934" "4875283").PN.	USPAT	2003/10/17 12:38
33	18	5153050.URPN.	USPAT	2003/10/17 12:38
34	6	("3990926" "4113576" "4394419" "5096522" "5120590" "5153050").PN.	USPAT	2003/10/17 12:40
42	1	"3969177".PN.	USPAT	2003/10/17 12:42
43	20	4875283.URPN.	USPAT	2003/10/17 12:40
44	2	("4875283").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 12:43
45	89	KARIYA-TAKASHI	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 12:46
46	17	JOHNSTON-JAMES-A	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 12:46
54	3424675	bond or bonding or bonded or laminate or laminating or laminated or join or joining or joined or mold or molded or molding or mould or moulded or moulding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 12:54
55	2342014	adhesive or resin or epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 12:53

59	34333	printed near board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 12:54
61	314278	(circuit near board) or (printed near board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 12:55
64	96	((circuit near board) or (printed near board)) same (bond or bonding or bonded or laminate or laminating or laminated or join or joining or joined or mold or molded or molding or mould or moulded or moulding) same (adhesive or resin or epoxy) same (multilayer or (multi near layer)) same stack	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 12:58